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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/824,577	04/14/2004	Chia-Chen Liu	252011-2230	6533	
47390	47390 7590 03/28/2006			EXAMINER	
THOMAS, KAYDEN, HOSTEMEYER & RISLEY LLP			PERKINS, PAMELA E		
SUITE 1750	WIIIIII WIII		ART UNIT	PAPER NUMBER	
ATLANTA,	GA 30339		2822		

DATE MAILED: 03/28/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application No.	Applicant(s)			
Office Action Summary		10/824,577	LIU ET AL.			
		Examiner	Art Unit			
		Pamela E. Perkins	2822			
The Period for Re	e MAILING DATE of this communication app eply	ears on the cover sheet with the c	orrespondence address			
WHICHE - Extensions after SIX (6 - If NO perio - Failure to r Any reply r	TENED STATUTORY PERIOD FOR REPLY VER IS LONGER, FROM THE MAILING DA of time may be available under the provisions of 37 CFR 1.13 b) MONTHS from the mailing date of this communication. If of or reply is specified above, the maximum statutory period we eply within the set or extended period for reply will, by statute, eceived by the Office later than three months after the mailing ent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim rill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).			
Status						
1)⊠ Res	sponsive to communication(s) filed on <u>26 De</u>	ecember 2005.				
2a)☐ This	This action is FINAL . 2b)⊠ This action is non-final.					
3)☐ Sind	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
clos	ed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 45	53 O.G. 213.			
Disposition of	of Claims					
4)⊠ Cla 4a) 5)⊡ Cla 6)⊠ Cla 7)⊡ Cla	im(s) <u>1-19,26 and 27</u> is/are pending in the a Of the above claim(s) is/are withdraw im(s) is/are allowed. im(s) <u>1-19,26 and 27</u> is/are rejected. im(s) is/are objected to.	n from consideration.				
8)∐ Clai	m(s) are subject to restriction and/or	election requirement.				
Application F	Papers					
10)⊠ The App Rep	specification is objected to by the Examiner drawing(s) filed on 14 April 2004 is/are: a) licant may not request that any objection to the diacement drawing sheet(s) including the correction oath or declaration is objected to by the Example 1.	☑ accepted or b)☐ objected to be drawing(s) be held in abeyance. See on is required if the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).			
Priority unde	r 35 U.S.C. § 119					
12)⊠ Ackr a)⊠ Al 1.⊠ 2.□ 3.□	nowledgment is made of a claim for foreign b) Some * c) None of: Certified copies of the priority documents Certified copies of the priority documents	have been received. have been received in Application ty documents have been received (PCT Rule 17.2(a)).	on No d in this National Stage			
	·					
Attachment(s)	references Cited (PTO-892)	4) []	(DTO 442)			
2) ☐ Notice of D 3) ☑ Information	praftsperson's Patent Drawing Review (PTO-948) Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal Pa				

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DETAILED ACTION

This office action is in response to the filing of the election on 26 December 2005. Claims 1-19, 26 and 27 are pending; claims 20-25 have been cancelled.

Election/Restrictions

Applicant's election without traverse of group I, claims 1-19 in the reply filed on 26 December 2005 is acknowledged.

Claims 20-25 are withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a nonelected group II, there being no allowable generic or linking claim. Election was made **without** traverse in the reply filed on 26 December 2005.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-19, 26 and 27 are rejected under 35 U.S.C. 103(a) as being unpatentable over Johnson (6,525,953) in view of Chakrabarti et al. (5,747,135).

Referring to claims 1, 14, 26 and 27, Johnson discloses a method of fabricating a semiconductor memory device where a first conductive layer (114), a first type doped semiconductor layer (130), a first dielectric layer (131), and a second type doped

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semiconductor layer (132) are sequentially formed on a substrate (100); patterning the second type doped semiconductor layer (132), the first dielectric layer (131), the first type doped semiconductor layer (130), and the conductive layer (114) along the first direction, thereby turning the conductive layer into a first conductive line; patterning the second type doped semiconductor layer (132), the first dielectric layer (131), and the first type doped semiconductor layer (130) into a memory cell; depositing a second dielectric layer (not shown) overlying the substrate (100); planarizing the second dielectric layer to expose the memory cell; and forming a second conductive line (123) overlying the second dielectric layer, running generally perpendicular to the first conductive line (Fig. 7; col. 8, line 36 thru col. 9, line 22; col. 11, lines 18-43).

Johnson does not disclose employing oxygen plasma sputtering to clean the substrate before deposition of a second dielectric layer.

Chakrabarti et al. disclose a method of fabricating a semiconductor memory device where a dielectric layer (16) is formed over a substrate (12), wherein oxygen plasma sputtering is employed to clean the substrate before deposition of the dielectric layer (col. 3, lines 21-37).

Since Johnson and Chakrabarti et al. are both from the same field of endeavor, a method of fabricating a semiconductor memory device, the purpose disclosed by Chakrabarti et al. would have been recognized in the pertinent art of Johnson.

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Johnson by employing oxygen plasma sputtering to clean

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the substrate before deposition of a dielectric layer as taught by Chakrabarti et al. to contaminants form the substrate (col. 3, lines 37-43).

Referring to claim 2 and 14, Johnson discloses the first type doped semiconductor layer as a p+ -type doped silicon layer (col. 11, lines 18-43).

Referring to claims 3 and 14, Johnson discloses the first conductive layer comprising a stack of TiN/TiSi2/p+-type doped silicon layers (col. 8, lines 45-53).

Referring to claims 4 and 14, Johnson discloses the first conductive line as a word line (Fig. 1; col. 4, lines 60-63).

Referring to claims 5 and 15, Johnson discloses the formation of the first dielectric layer comprises rapid thermal oxidation of silicon (col. 8, lines 61-67).

Referring to claims 6 and 14, Johnson discloses the second type doped silicon layer is n-type doped silicon layer (col. 11, lines 18-43).

Referring to claims 7 and 14, Johnson discloses the memory cell comprises a stack of p+-type doped silicon/first dielectric/n-type doped silicon layers (Fig. 7; col. 11, lines 18-43).

Referring to claims 12 and 14, Johnson discloses the second conductive layer comprises a stack of n+-type doped silicon/TiN/TiS₂/n+-type doped silicon/n-type doped silicon layers (Fig. 7; col. 11, lines 18-43).

Referring to claim s13 and 14, Johnson disclose the second conductive line as a bit line (Fig. 1; col. 4, lines 60-63).

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Referring to claims 8-11 and 16-19, Chakrabarti et al. do not disclose a flow rate between 200 and 400sccm, a temperature between 225 and 275 °C and power between 1000 and 1500W. It would have been obvious to one having ordinary skill in the art at the time invention was made to perform oxygen plasma cleaning at a flow rate between 200 and 400sccm, a temperature between 225 and 275 °C and power between 1000 and 1500W disclosed in the claimed invention, since it has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or workable ranges involves only routine skill in the art. *In re Aller*, 105 USPQ 233 (CCPA 1955).

Conclusion

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Lung et al. (6,984,548) disclose a three-dimensional memory array.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Pamela E. Perkins whose telephone number is (571) 272-1840. The examiner can normally be reached on Monday thru Friday, 8:30am to 5:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra Smith can be reached on (571) 272-2429. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

PEP

Supervisory Patent Examiner

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